

Multilayer Ceramic Chip Capacitors

C3225X7R1A226K230AC









TDK item description C3225X7R1A226KT****

Applications	Commercial Grade	
Feature	General General (Up to 50V)	
Series	C3225 [EIA 1210]	
Status	Production	



	Size	
Length(L)	3.20mm ±0.40mm	
Width(W)	2.50mm ±0.30mm	
Thickness(T)	2.30mm ±0.20mm	
Terminal Width(B)	0.20mm Min.	
Terminal Spacing(G)		
Recommended Land Pattern (PA)	2.00mm to 2.40mm	
Recommended Land Pattern (PB)	1.00mm to 1.20mm	-
Recommended Land Pattern (PC)	1.90mm to 2.50mm	

Electrical Characteristics		
Capacitance	22μF ±10%	
Rated Voltage	10VDC	
Temperature Characteristic	X7R(±15%)	
Dissipation Factor (Max.)	7.5%	
Insulation Resistance (Min.)	4ΜΩ	

Other	
Soldering Method	Reflow
AEC-Q200	No
Packing	Blister (Plastic)Taping [180mm Reel]
Package Quantity	1000pcs

[!] Images are for reference only and show exemplary products. ! This PDF document was created based on the data listed on the TDK Corporation website.

[!] All specifications are subject to change without notice.

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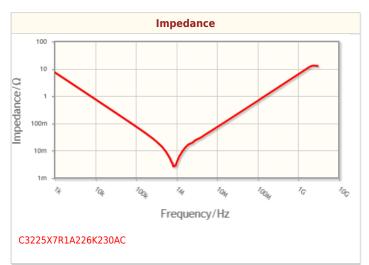


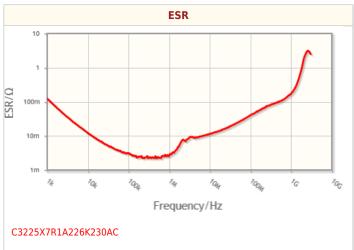


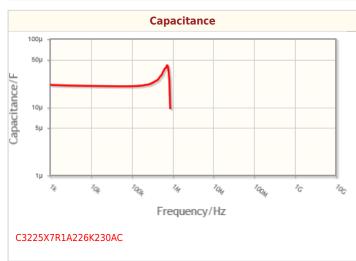


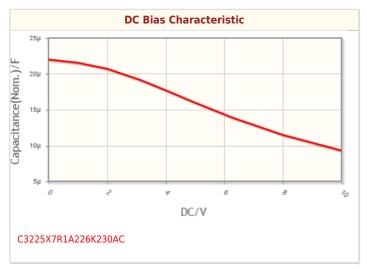


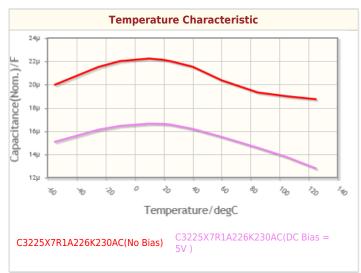
Characteristic Graphs(This is reference data, and does not guarantee the products characteristics.)

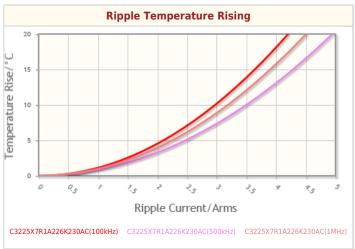












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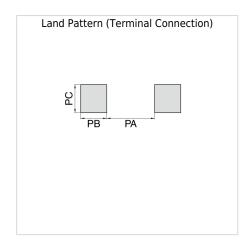








Associated Images



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